

# SN54LS597, SN54LS598, SN74LS597, SN74LS598 8-BIT SHIFT REGISTERS WITH INPUT LATCHES

SDLS007

D2635, JANUARY 1981—REVISED MARCH 1988

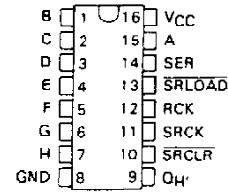
- 8-Bit Parallel Storage Register Inputs ('LS597)
- Parallel 3-State I/O, Storage Register Inputs, Shift Register Outputs ('LS598)
- Shift Register has Direct Overriding Load and Clear
- Accurate Shift-Frequency . . . DC to 20 MHz

## description

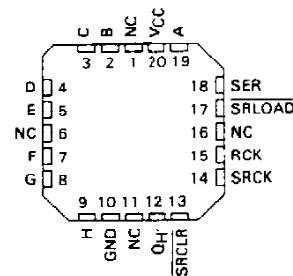
The 'LS597 comes in a 16-pin package and consists of an 8-bit storage latch feeding a parallel-in, serial-out 8-bit shift register. Both the storage register and shift register have positive-edge triggered clocks. The shift register also has direct load (from storage) and clear inputs.

The 'LS598 comes in a 20-pin package and has all the features of the 'LS597 plus 3-state I/O ports that provide parallel shift register outputs and also has multiplexed serial data inputs.

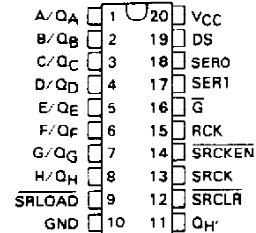
SN54LS597 . . . J OR W PACKAGE  
SN74LS597 . . . N PACKAGE  
(TOP VIEW)



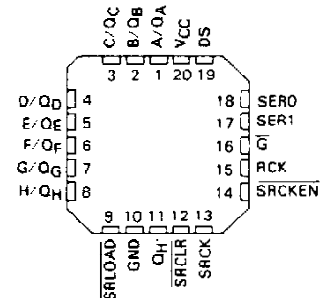
SN54LS597 . . . FK PACKAGE  
(TOP VIEW)



SN54LS598 . . . J OR W PACKAGE  
LS598 . . . DW OR N PACKAGE  
(TOP VIEW)



SN54LS598 . . . FK PACKAGE  
(TOP VIEW)



NC - No internal connection

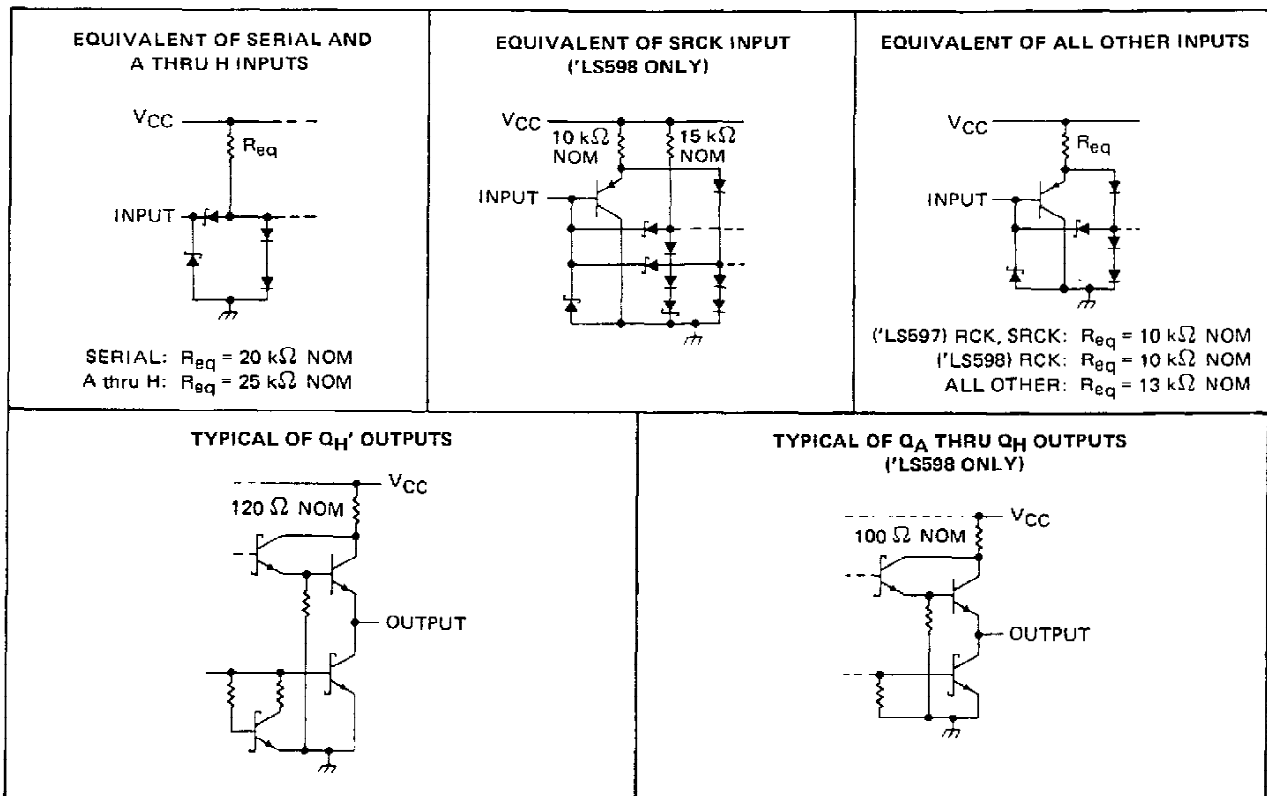
PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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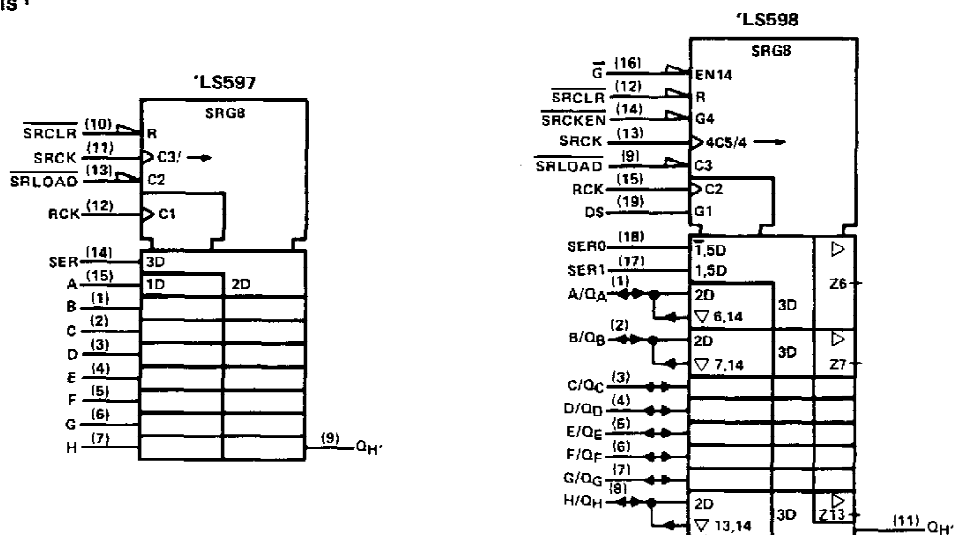
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# SN54LS597, SN54LS598, SN74LS597, SN74LS598 8-BIT SHIFT REGISTERS WITH INPUT LATCHES

schematics of inputs and outputs



logic symbols†



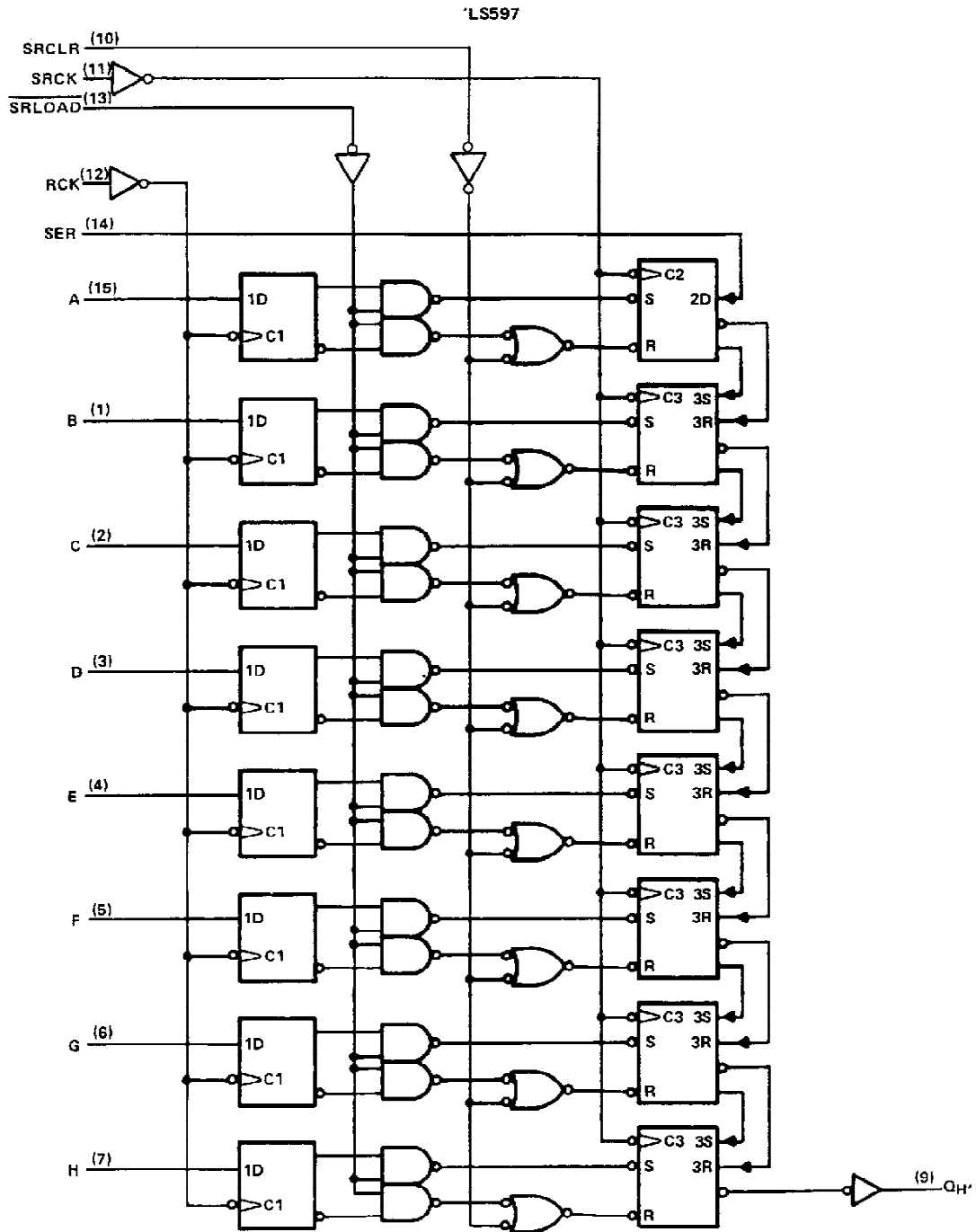
†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, N, and W packages.

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**SN54LS597, SN74LS597**  
**8-BIT SHIFT REGISTERS WITH INPUT LATCHES**

logic diagram (positive logic)



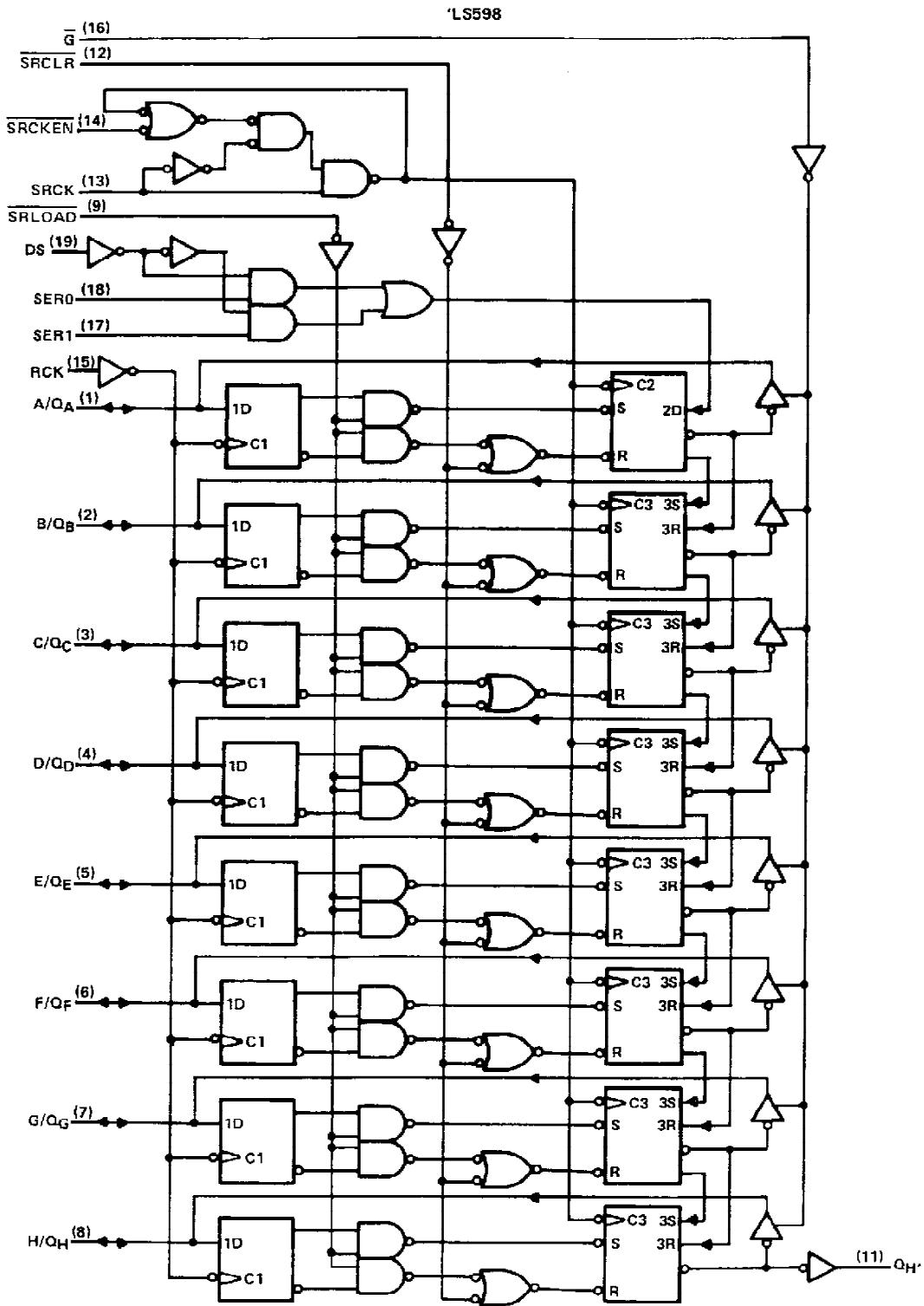
Pin numbers shown are for DW, J, N, and W packages.

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# SN54LS598, SN74LS598 8-BIT SHIFT REGISTERS WITH INPUT LATCHES

logic diagram (positive logic)



Pin numbers shown are for DW, J, N, and W packages.

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# SN54LS597, SN54LS598, SN74LS597, SN74LS598 8-BIT SHIFT REGISTERS WITH INPUT LATCHES

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, $V_{CC}$ (see Note 1) .....	7 V
Input voltage (excluding I/O ports) .....	7 V
Off-state output voltage (including I/O ports) .....	5.5 V
Operating free-air temperature range: SN54LS597, SN54LS598 .....	$-55^{\circ}\text{C}$ to $125^{\circ}\text{C}$
SN74LS597, SN74LS598 .....	$0^{\circ}\text{C}$ to $70^{\circ}\text{C}$
Storage temperature range .....	$-65^{\circ}\text{C}$ to $150^{\circ}\text{C}$

NOTE 1: Voltage values are with respect to the network ground terminal.

## recommended operating conditions

		SN54LS'			SN74LS'			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX		
$V_{CC}$	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
$V_{IH}$	High-level input voltage	2			2			V	
$V_{IL}$	Low-level input voltage				0.7			V	
$I_{OH}$	High-level output current	$Q_H'$		-1		-1		mA	
		$Q_A$ thru $Q_H$ , 'LS598 only		-1		-2.6			
$I_{OL}$	Low-level output current	$Q_H'$		8		16		mA	
		$Q_A$ thru $Q_H$ , 'LS598 only		12		24			
$f_{SCK}$	Shift clock frequency	0		20		0		20	MHz
$t_w$	Pulse duration	SRCK	high	15		15		ns	
			low	35		35			
		RCK		20		20			
		SRCLR		20		20			
		SRLOAD		40		40			
$t_{su}$	Setup time	Data before RCK $\uparrow$		20		20		ns	
		DS before SRCK $\uparrow$ ('LS598 only)		30		30			
		SRCKEN low before SRCK $\uparrow$ ('LS598 only)		20		20			
		SRCLR inactive before SRCK $\uparrow$		25		25			
		SRLOAD inactive before SRCK $\uparrow$		30		30			
		RCK $\uparrow$ before SRLOAD $\uparrow$ (see Note 2)		40		40			
		SER before SRCK $\uparrow$		20		20			
$t_h$	Hold time	0		0		0		ns	
$T_A$	Operating free-air temperature	-55		125		0		70	$^{\circ}\text{C}$

NOTE 2: The RCK  $\uparrow$  before SRLOAD  $\uparrow$  setup time ensures the data saved by RCK  $\uparrow$  will also be loaded into the shift register.



**SN54LS597, SN54LS598, SN74LS597, SN74LS598**  
**8-BIT SHIFT REGISTERS WITH INPUT LATCHES**

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS*		SN74LS*		UNIT		
		MIN	TYP‡	MAX	MIN		TYP‡	MAX
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA			-1.5		-1.5	V	
V <sub>OH</sub>	'LS598 Q Q <sub>H</sub> '	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = MAX	I <sub>OH</sub> = -1 mA	2.4	3.2			
			I <sub>OH</sub> = -2.6 mA			2.4	3.1	
V <sub>OL</sub>	'LS598 Q Q <sub>H</sub> '	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = MAX	I <sub>OL</sub> = 12 mA		0.25	0.4	0.25	0.4
			I <sub>OL</sub> = 24 mA				0.35	0.5
			I <sub>OL</sub> = 8 mA		0.25	0.4	0.25	0.4
			I <sub>OL</sub> = 16 mA				0.35	0.5
I <sub>OZH</sub>	'LS598 Q	V <sub>CC</sub> = MAX, V <sub>O</sub> = 2.7 V	V <sub>IH</sub> = 2 V, V <sub>IL</sub> = MAX,			20	20	μA
I <sub>OZL</sub>	'LS598 Q	V <sub>CC</sub> = MAX, V <sub>O</sub> = 0.4 V	V <sub>IH</sub> = 2 V, V <sub>IL</sub> = MAX,			-0.4	-0.4	mA
I <sub>I</sub>	'LS598 Q	V <sub>CC</sub> = MAX	V <sub>I</sub> = 5.5 V			0.1	0.1	mA
	Others		V <sub>I</sub> = 7 V			0.1	0.1	
I <sub>IH</sub>		V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V				20	20	μA
I <sub>IL</sub>	'LS598 SRCK	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V				-0.8	-0.8	mA
	SER, A Thru H					-0.4	-0.4	
	Others					-0.2	-0.2	
I <sub>OS</sub> §	'LS598 Q	V <sub>CC</sub> = MAX, V <sub>O</sub> = 0 V				-30	-130	mA
	Q <sub>H</sub> '					-20	-100	
I <sub>CC</sub>	'LS597	V <sub>CC</sub> = MAX, All possible inputs grounded, All outputs open	I <sub>CC</sub> H	35	53	35	53	mA
			I <sub>CC</sub> L	35	53	35	53	
	'LS598		I <sub>CC</sub> H	45	68	45	68	
			I <sub>CC</sub> L	54	80	54	80	
			I <sub>CC</sub> Z	56	85	56	85	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

§ Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

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**8-BIT SHIFT REGISTERS WITH INPUT LATCHES**

switching characteristics,  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ . (see note 3)

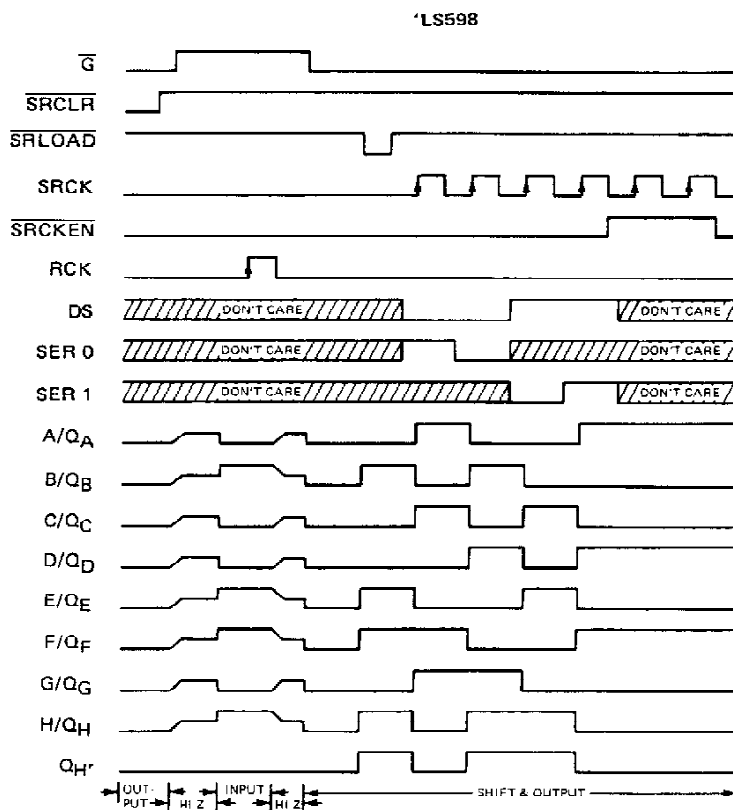
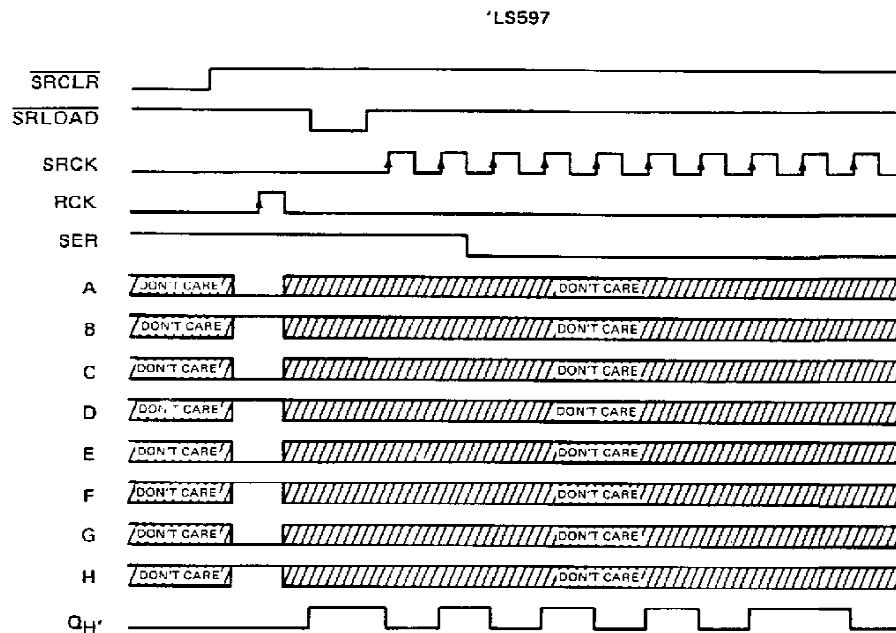
PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	LS597			LS598			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
$f_{max}$	SRCK	Q	$R_L = 667\ \Omega$ , $C_L = 45\ \mu\text{F}$	20	35		20	35		MHz
$f_{max}$	SRCK	$Q_H'$	$R_L = 1\ \text{k}\Omega$ , $C_L = 30\ \text{pF}$	20	35					MHz
$t_{PLH}$	SRCK $\uparrow$	$Q_H'$	$R_L = 1\ \text{k}\Omega$ , $C_L = 30\ \text{pF}$		15	23		11	17	ns
$t_{PHL}$	SPCK $\uparrow$	$Q_H'$			20	30		15	23	ns
$t_{PLH}$	$\overline{\text{SRLOAD}}\downarrow$	$Q_H'$			38	57		28	42	ns
$t_{PHL}$	$\overline{\text{SRLOAD}}\downarrow$	$Q_H'$			29	44		20	30	ns
$t_{PHL}$	SRCLR $\downarrow$	$Q_H'$			24	36		18	27	ns
$t_{PLH}$	RCK $\uparrow$	$Q_H'$	$R_L = 1\ \text{k}\Omega$ , $C_L = 30\ \text{pF}$ SRLOAD = L	41	60		32	48		ns
$t_{PHL}$	RCK $\uparrow$	$Q_H'$			32	48		24	36	ns
$t_{PLH}$	SRCK $\uparrow$	Q	$R_L = 667\ \Omega$ , $C_L = 45\ \text{pF}$					12	18	ns
$t_{PHL}$	SRCK $\uparrow$	Q						19	28	ns
$t_{PLH}$	$\overline{\text{SRLOAD}}\downarrow$	Q						32	48	ns
$t_{PHL}$	$\overline{\text{SRLOAD}}\downarrow$	Q						27	40	ns
$t_{PHL}$	SRCLR $\downarrow$	Q						25	38	ns
$t_{PZH}$	G $\downarrow$	Q						26	31	ns
$t_{PZL}$	G $\downarrow$	Q						29	43	ns
$t_{PHZ}$	G $\uparrow$	Q	$R_L = 667\ \Omega$ , $C_L = 5\ \text{pF}$					25	38	ns
$t_{PLZ}$	G $\uparrow$	Q						20	30	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



# SN54LS597, SN54LS598, SN74LS597, SN74LS598 8-BIT SHIFT REGISTERS WITH INPUT LATCHES

typical operating sequences



  
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**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-89444012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8944401EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8944401EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8944401FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-8944401FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-89756012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
5962-89756012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
5962-8975601SA	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI
5962-8975601SA	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI
SN54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SN54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SN74LS597D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS597N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS597NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS597NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS597NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LS597NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS598N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS598NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS598NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54LS597FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS597FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS597W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS597W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS598FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS598FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SNJ54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SNJ54LS598W	OBSOLETE			20		TBD	Call TI	Call TI
SNJ54LS598W	OBSOLETE			20		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

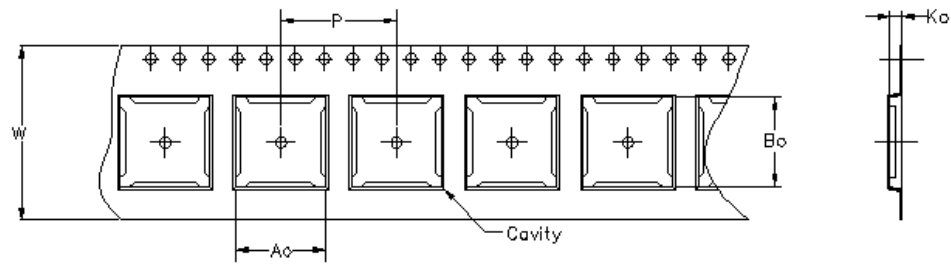
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

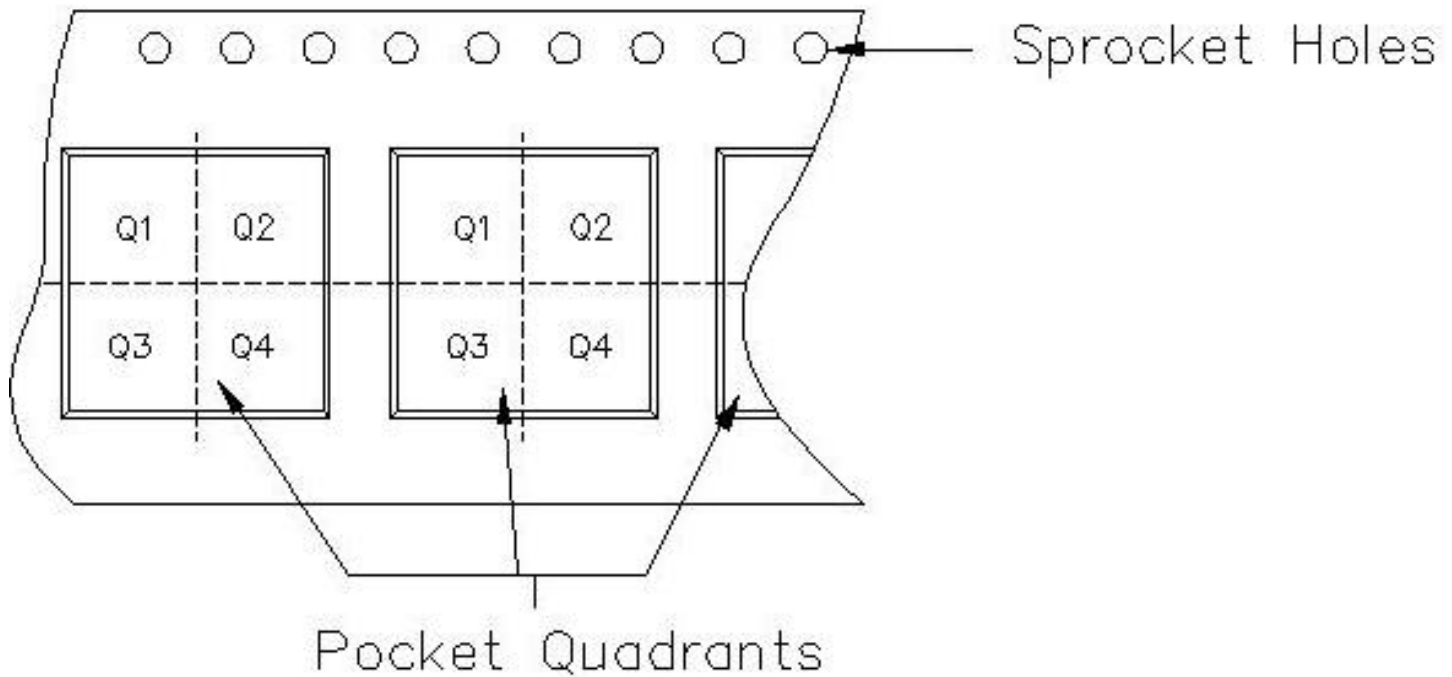
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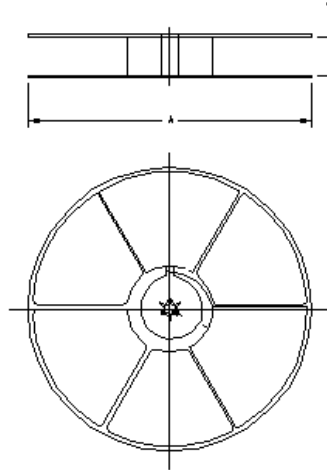
Carrier tape design is defined largely by the component length, width, and thickness.

$A_o$ = Dimension designed to accommodate the component width.
$B_o$ = Dimension designed to accommodate the component length.
$K_o$ = Dimension designed to accommodate the component thickness.
$W$ = Overall width of the carrier tape.
$P$ = Pitch between successive cavity centers.



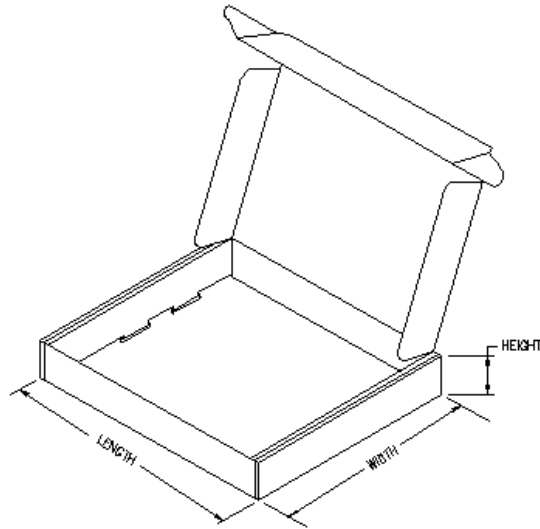
**TAPE AND REEL INFORMATION**

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS597DR	D	16	FMX	330	16	6.5	10.3	2.1	8	16	Q1
SN74LS597NSR	NS	16	MLA	330	16	8.2	10.5	2.5	12	16	Q1



**TAPE AND REEL BOX INFORMATION**

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74LS597DR	D	16	FMX	342.9	336.6	28.58
SN74LS597NSR	NS	16	MLA	342.9	336.6	28.58



J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

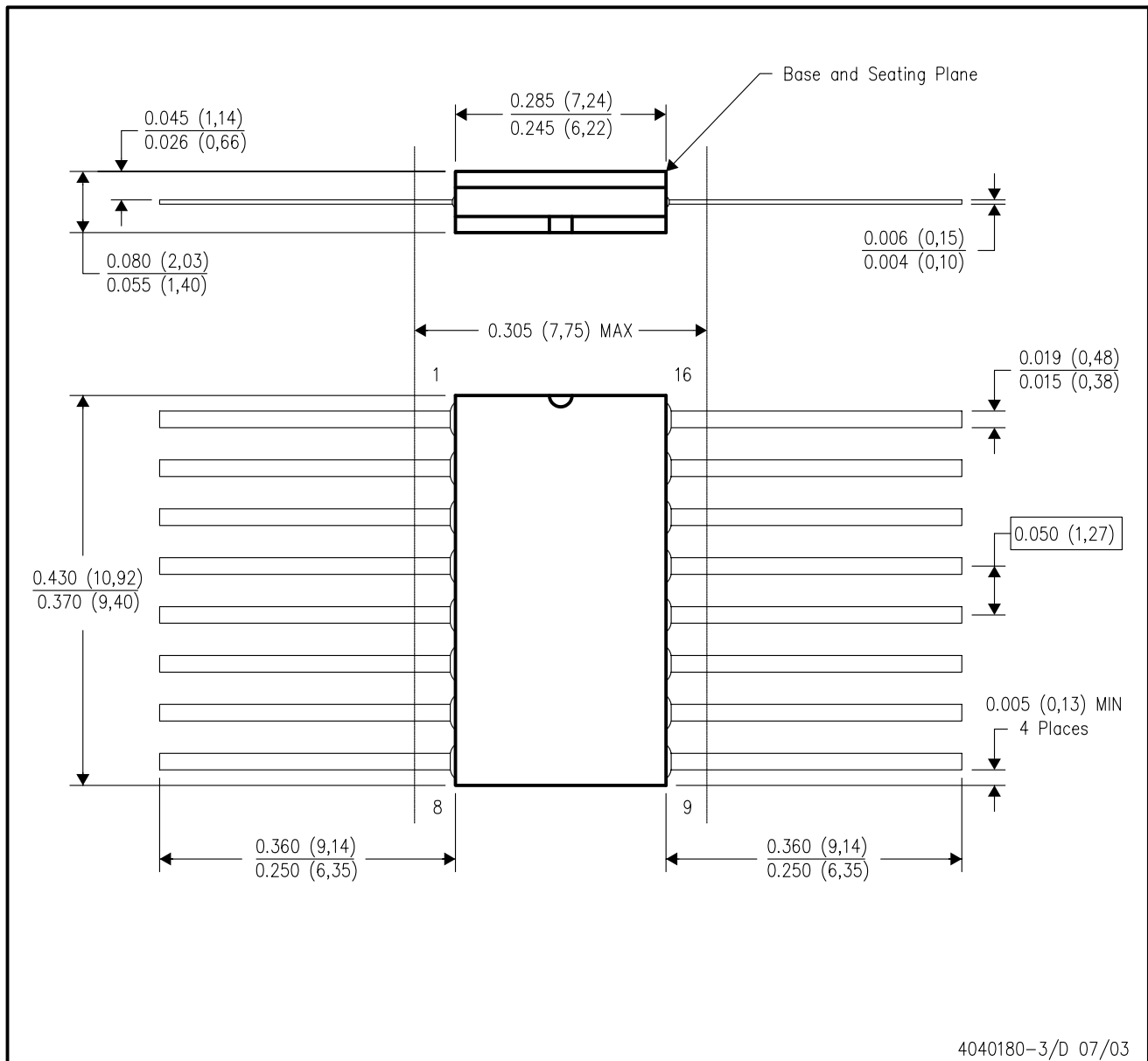


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

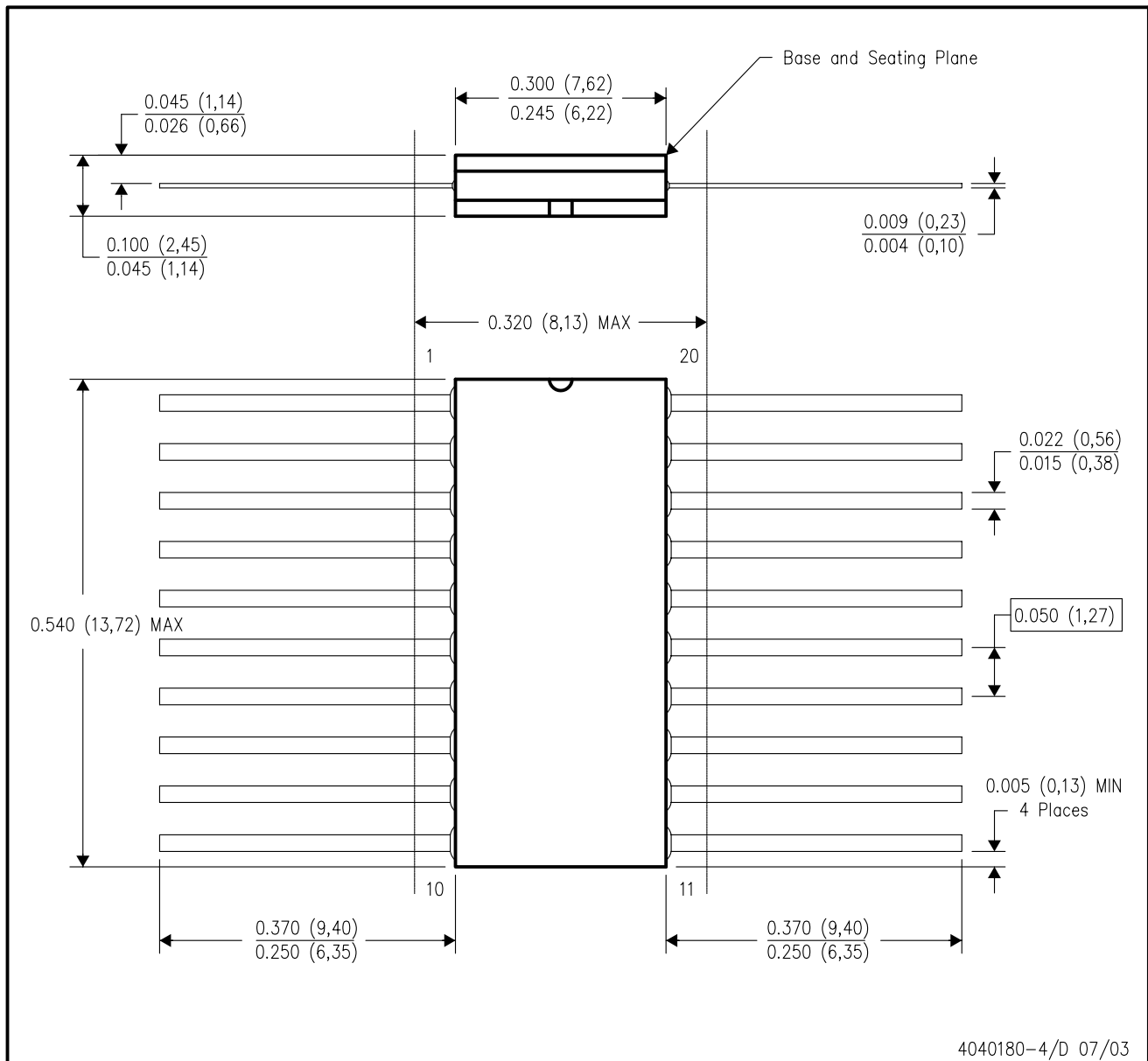
CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-89444012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8944401EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8944401EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8944401FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-8944401FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-89756012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
5962-89756012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
5962-8975601SA	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI
5962-8975601SA	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI
SN54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SN54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SN74LS597D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS597N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS597NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS597NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS597NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LS597NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS597NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS598N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS598N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS598NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS598NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54LS597FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS597FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS597W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS597W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS598FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS598FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SNJ54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SNJ54LS598W	OBSOLETE			20		TBD	Call TI	Call TI
SNJ54LS598W	OBSOLETE			20		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

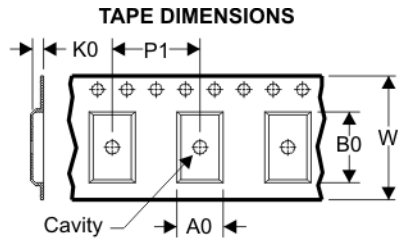
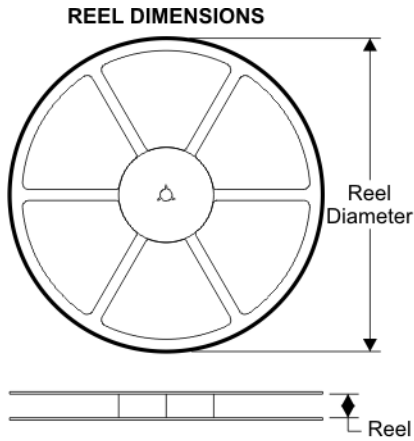
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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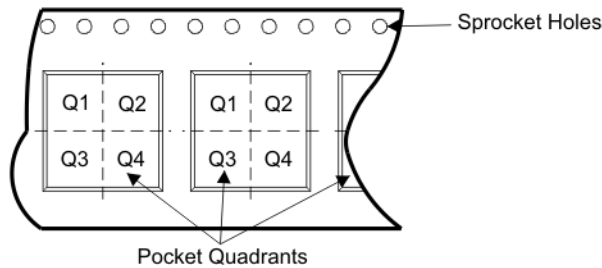
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**TAPE AND REEL BOX INFORMATION**



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS597DR	D	16	SITE 27	330	16	6.5	10.3	2.1	8	16	Q1
SN74LS597NSR	NS	16	SITE 41	330	16	8.2	10.5	2.5	12	16	Q1

**TAPE AND REEL BOX DIMENSIONS**



Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74LS597DR	D	16	SITE 27	342.9	336.6	28.58
SN74LS597NSR	NS	16	SITE 41	346.0	346.0	33.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

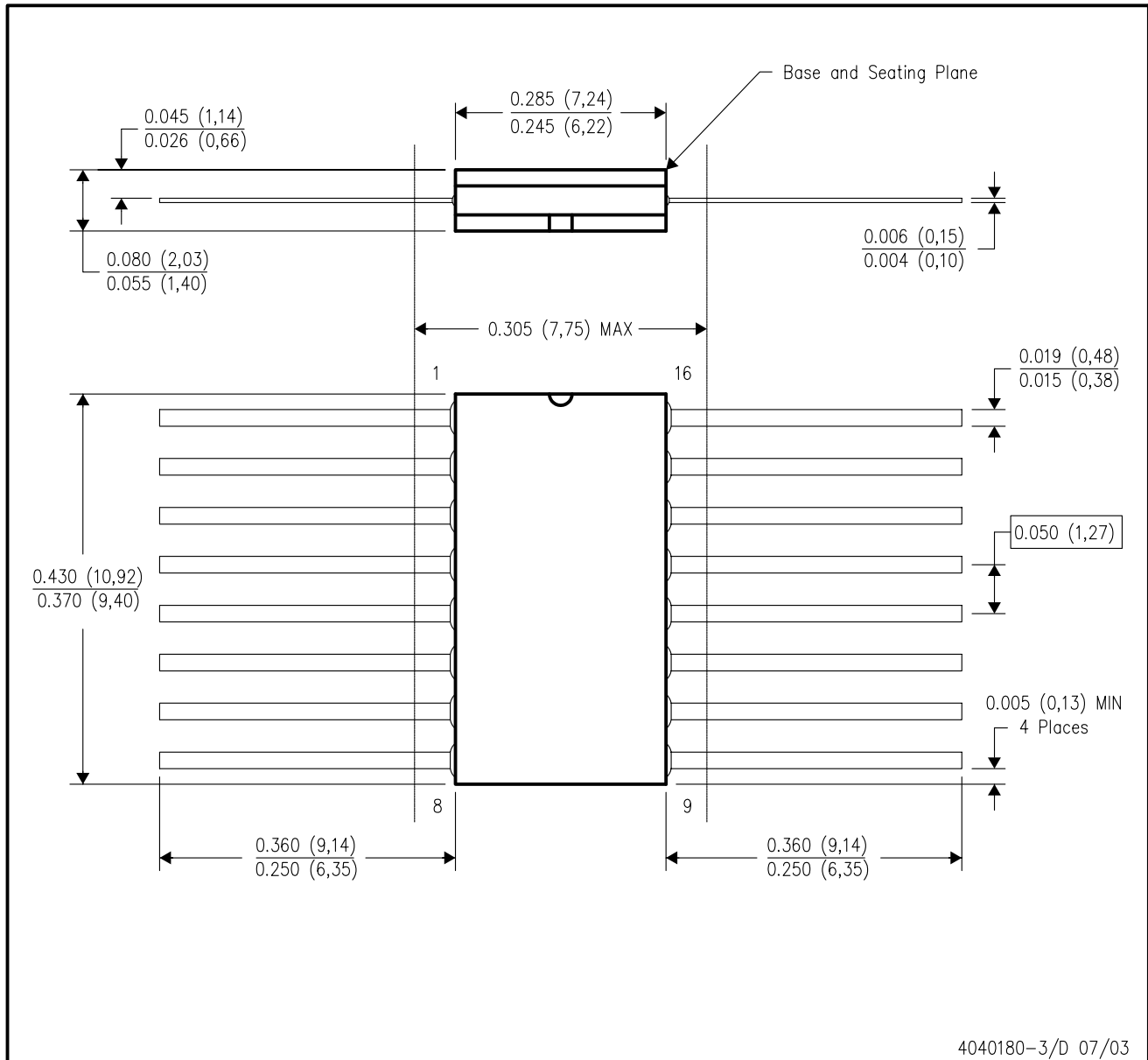


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

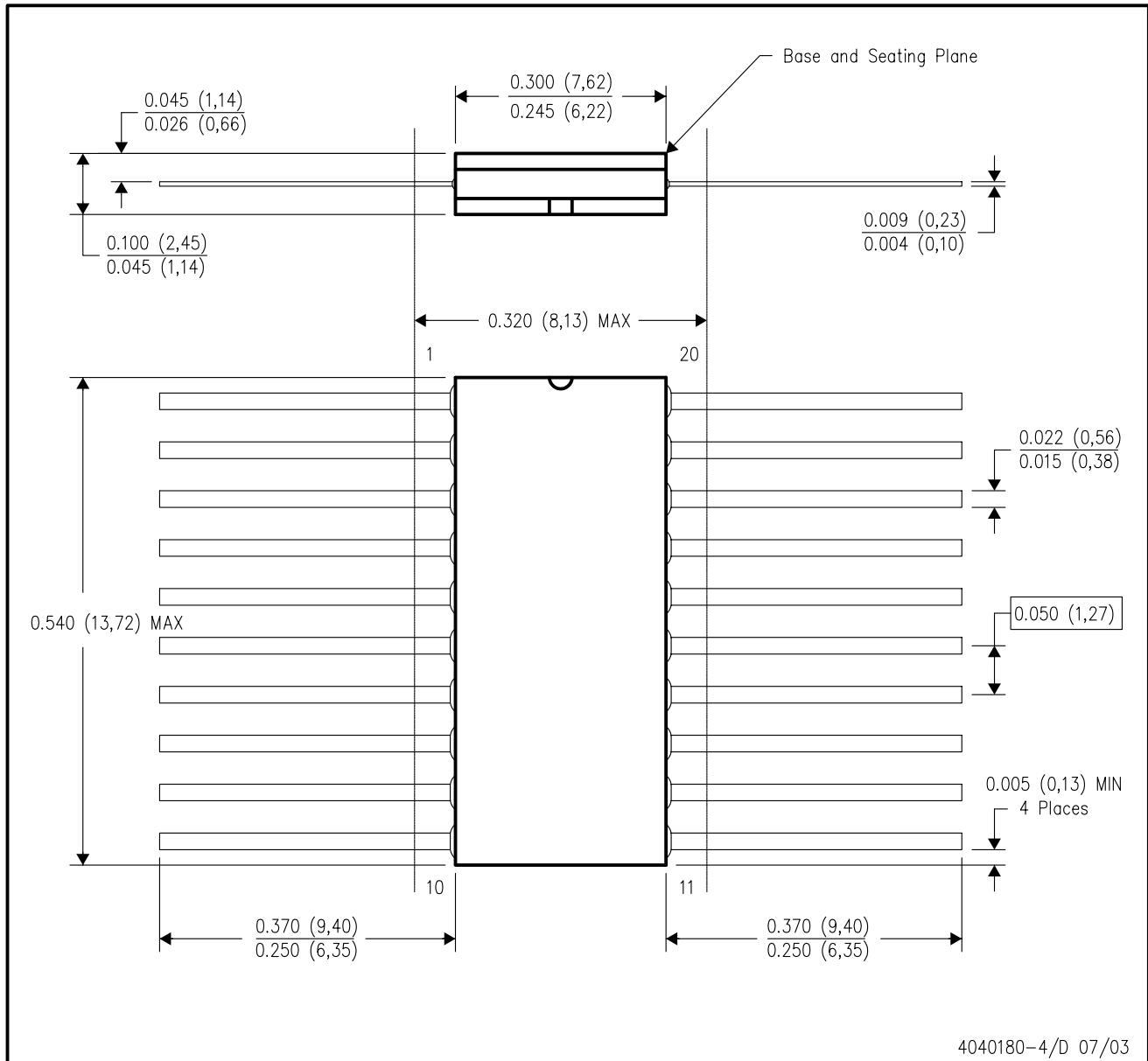
CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only.
  - Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



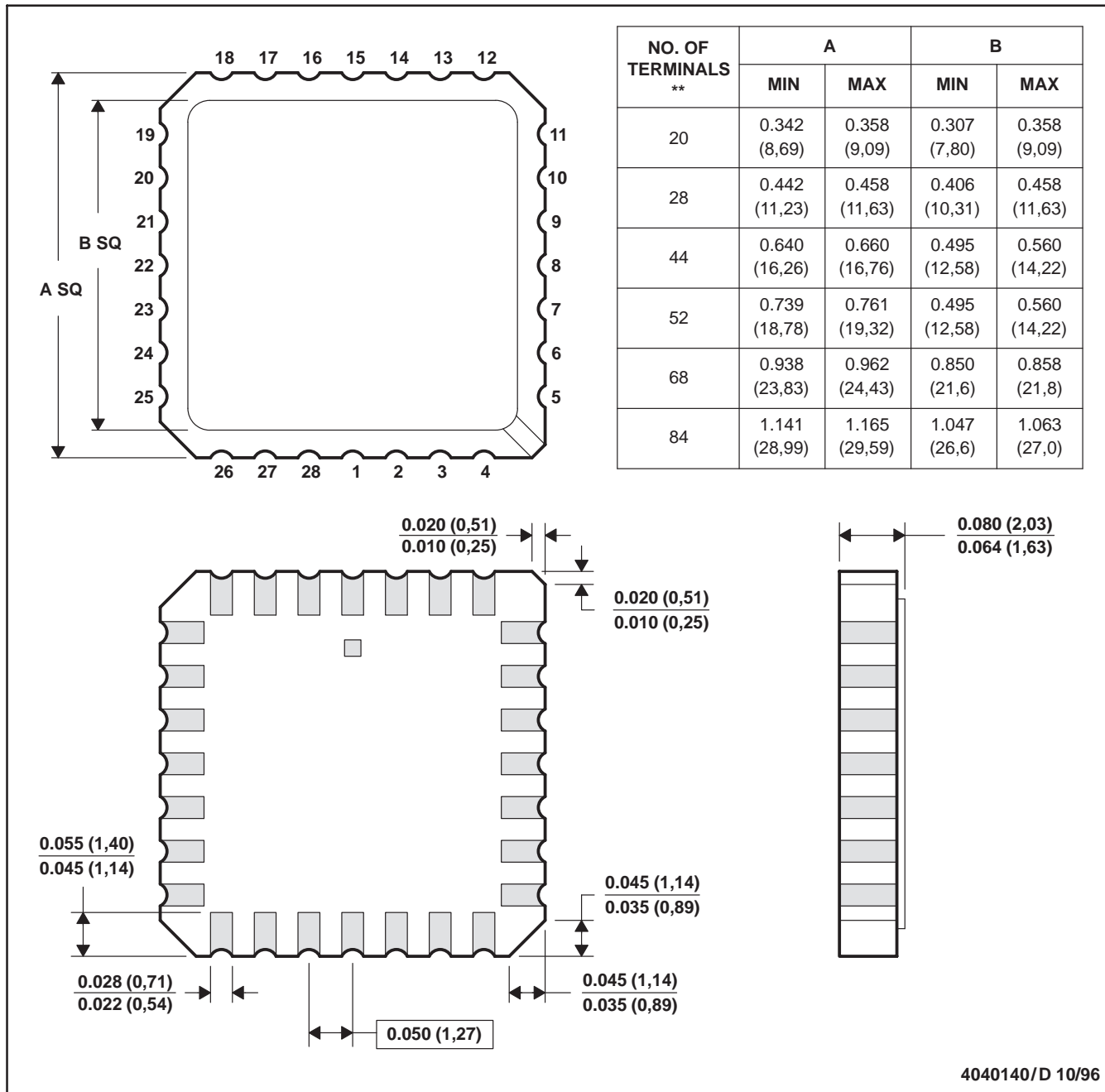
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20



FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

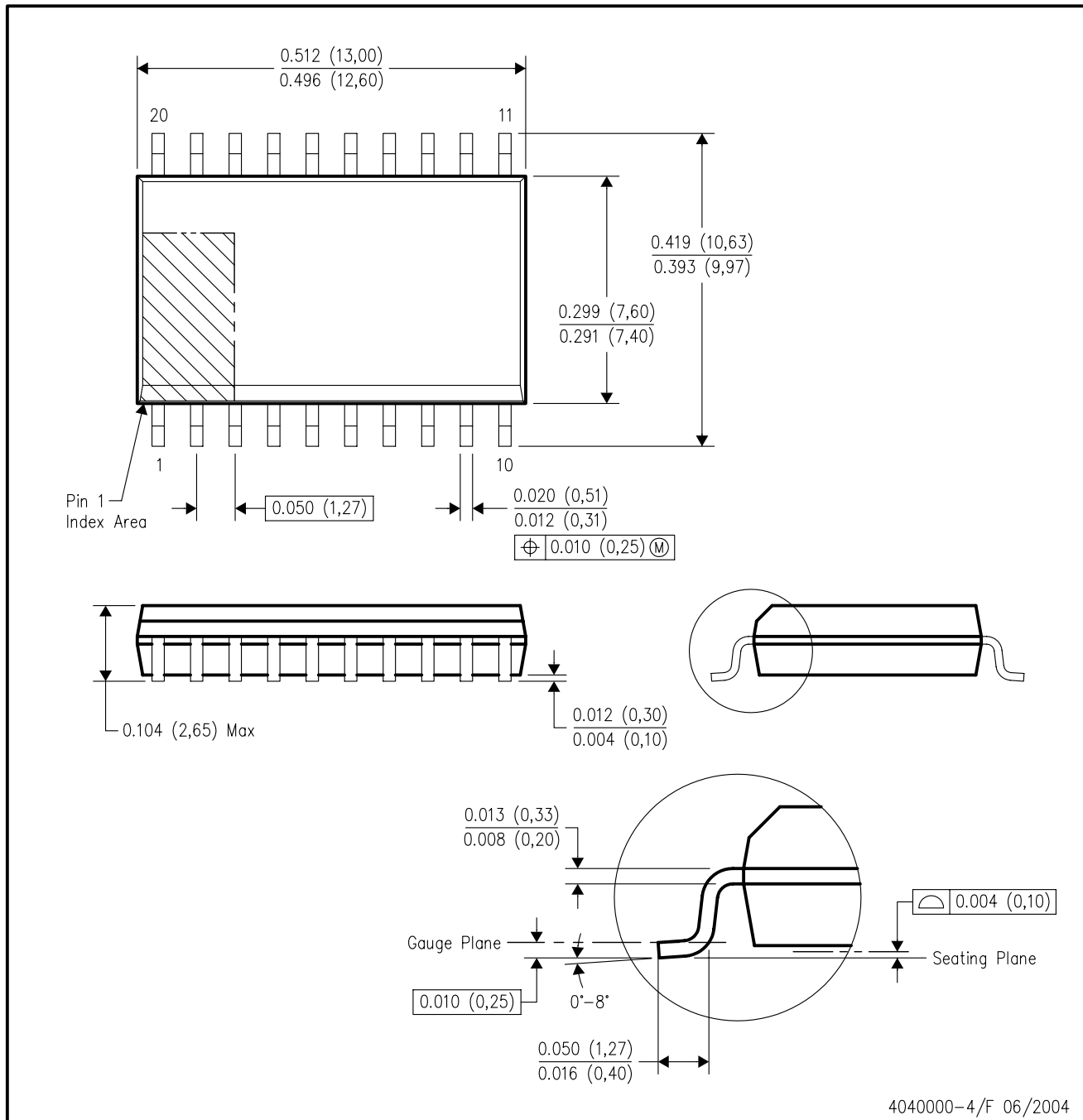
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

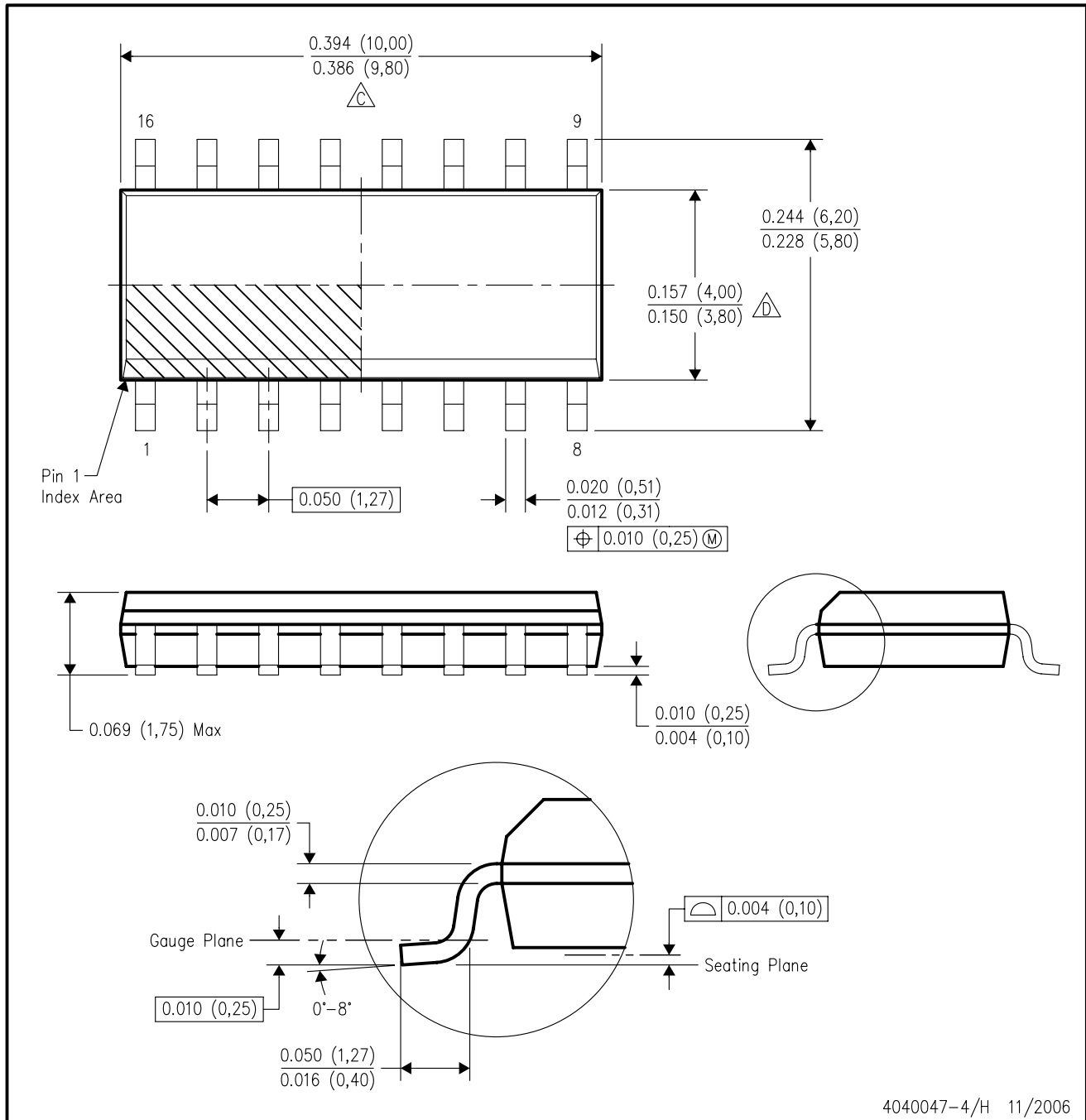
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - △ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - △ Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AC.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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Low Power Wireless	<a href="http://www.ti.com/lpw">www.ti.com/lpw</a>	Video & Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>
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